

Ceramic tape for microwave LTCC substrates

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Who are we?

Patent information

**Technology
readiness
level:**
7

Title: Ceramic tape for microwave LTCC substrates

Patent number: Pat.241887

Priority Date: 9.03.2018

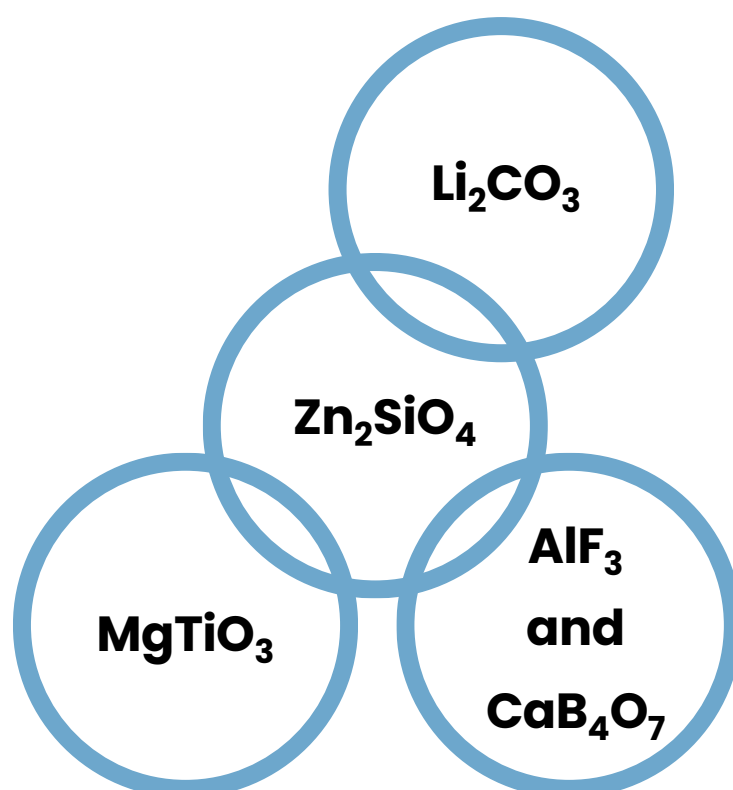
Inventors: Beata Synkiewicz – Musialska, Dorota Szwagierczak, Jan Kulawik

Owners: Łukasiewicz – IMiF

Jurisdictions: Poland

The subject of the invention is a ceramic tape for substrates and packages, produced by LTCC (Low Temperature Cofired Ceramics) technology. Our tape can be sintered at low temperatures (900–980°C) and exhibits low dielectric permittivity in the 1 kHz – 3 THz frequency after sintering.

Ceramic tape for microwave system substrates according to presented invention contains, after a sintering process, zinc silicate (Zn_2SiO_4) and magnesium titanate (MgTiO_3) or zinc silicate (Zn_2SiO_4) and lithium carbonate (Li_2CO_3) or zinc silicate (Zn_2SiO_4) and a mixture consisting of aluminum fluoride (AlF_3) and calcium borate (CaB_4O_7).



The potential behind the technology

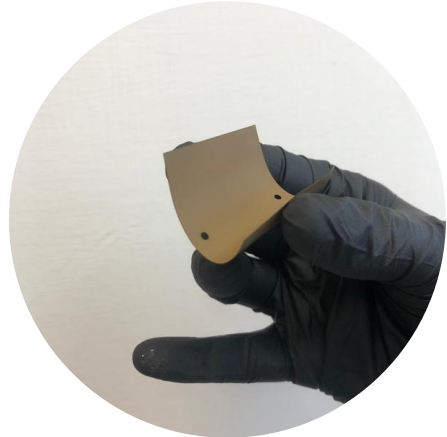
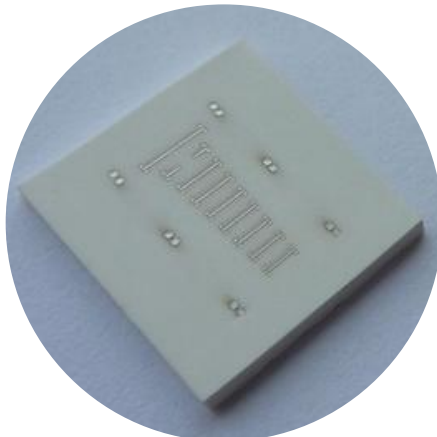
The ceramic tapes obtained according to the patent, show a low dielectric constant and a relatively low sintering temperature, making them a promising material for multilayer LTCC substrates for electronic circuits operating at very high frequencies. Thanks to our solution it can be possible to increase the speed of signal propagation, increase selectivity, reduce attenuation, and reduce power loss.

Technology Advantages

Our tape has a low sintering temperature of 900–980°C and no undesirable reactivity with silver and silver-palladium pastes used for screen-printing of conductive layers. In the sintered state, it has a dielectric constant of 6.0–7.2 at 1 MHz in the temperature range from –30 to 150°C and a loss factor of less than 0.003. The dielectric constant at room temperature is 6.1–7.2 at 1 THz .

Application

Our solution can be applied in substrates and packages for microwave circuits mainly destined for wireless communications (i.e., in devices related to satellite broadcasting, ultra-high-speed local area network LANs, electronic transport cashing (ETC), in-vehicle collision avoidance systems (intelligent transport systems ITS, etc.) and in devices where very high frequencies are used.



Collaboration type

License agreement or sale agreement

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